Package Delaying Services at EAG

PCB or Package samples can be delayered and examined at each layer. This is helpful in looking for opens, shorts, leakage and damage in the layers as well as design rule distances with in such samples. Packages can also be removed to allow analysis from the backside of die.

The device is then polished away layer by layer so that examination, images and analysis can be performed as needed.
The exposure of the die and the wire bonds allows Emission/OBIRCH/IR techniques to be applied to the device.